

REMARKS

Claims 1-7 are in the application as filed. Claims 5-7 are withdrawn from consideration due to restriction requirement. The Election of Claims 1-4 is confirmed. Traverse of the restriction requirement is argued below.

Claim 4 was objected to as multiply dependent and as dependent itself upon a multiply dependent claim. Claim 4 has been amended to remove the multiple dependency problem.

TRAVERSE OF THE RESTRICTION REQUIREMENT

Claims 5-7 were withdrawn as related to an intermediate and to a final product using the intermediate product of Claims 1-4. Applicant respectfully requests that Claims 5-7 be rejoined to the invention currently restricted to Claims 1-4. Claim 5 -7 are related to the uses of Claims 1-4. If Claims 1-4 prove patentable, items using these specific paste compositions should also be patentable.

REJECTION UNDER 35 USC 102 and 103

Claims 1-3 are rejected as anticipated under 35 USC 102(a) or, in the alternative as obvious under 35 USC 103(a) over JP 2002-80675. JP 2002-80675 is cited as disclosing an acrylic binder-type resin composition for baking-mould paste, which can impart high viscosity to the paste by its use in small amounts and has good properties in baking. The cited invention '675 uses various fillers and an acrylic polymer binder resin.

Within this binder composition there are the following ingredients:

400 -1900 mass parts of organic -solvent (B) in which 50 mass % or more of aromatic hydrocarbon content alcohol of boiling point 200 degrees C or more... was compounded to

100 mass parts of thermoplastic acrylic polymer (A) the range of whose weight average molecular weight is 1,000,000-6,000,000; this thermoplastic acrylic polymer is 80-100 mass % of at least 1 type (a-1) chosen from C1-C4 alkyl (meth) acrylate monomer; 0-10 mass % of 9(meth)acrylate monomer;

(a-2) containing a hydroxyl group, and the other monomer mixtures containing 0-10 mass % of monomer

(a-3) which can be co-polymerized.

The B-type viscosity at 25 degrees C is related to the acrylic resin-binder composition for baking-mould paste which is 10,000 or more mPa's.

The Examiner asserts that the cited reference either specifically or inherently meets all the limitations of applicant's claims. Applicants respectfully disagree with the Examiner's assessment that their claims are not patentable over the reference.

The presently claimed invention, as currently amended, is an electrically conductive paste firable in a neutral or reducing atmosphere comprising the following ingredients:

(a) 30 to 71 wt % conductive powder being selected from the group of copper powder, nickel powder and copper-nickel alloy powder and

(b) an inorganic binder, both dispersed in an inert organic medium; wherein the organic medium comprises at least one methyl methacrylate (MMA) polymer dissolved in solvent, said methyl methacrylate polymer having a number-average molecular weight of at least 100,000 and a weight-average molecular weight of at least 1,000,000, such that the methyl methacrylate polymer accounts for 2.0 to 9.0 wt % of the paste, where the amount of the inorganic binder is in the range from 5 to 15 wt %, wherein the inorganic binder is selected from Si-B-Ba glass, Si-B-Pb glass, Si-B-Zn glass, or mixtures thereof, and the conductive powder and inorganic binder combined is in the range from 45.0 wt % to 76 wt %. The present conductive paste also includes an embodiment wherein the organic medium further comprises ethyl methacrylate, butyl methacrylate, copolymers of acrylate compounds, or mixtures thereof.

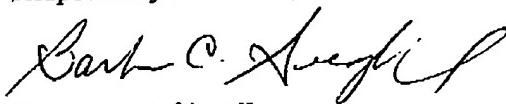
Although the JP 2002-80675 reference makes some general mention of metallic powders and fillers, such as glass, it does not teach the above current specific ratios of conductive power and organic and inorganic binder compositions.

In view of these differences and in view of the above amendments to applicant's claims, allowance of Claim 1 and 3 is respectfully requested and rejoinder of Claims 5-7 is requested.

If anything further is required to advance the allowance of this application, the Examiner is urged to contact applicants' attorney at the telephone number below.

Should any fee be required in connection with the filing of this Amendment please charge such fee to Deposit Account No. 04-1928 (E. I. du Pont de Nemours and Company).

Respectfully submitted,



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Enclosures